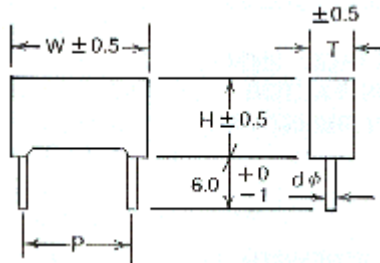


MEB is constructed with metallized polyester film dielectric, copper lead, encapsulated in plastic case with epoxy resin sealed. It is suitable for filtering, bypass, decoupling, coupling blocking, timing circuit and ideal for use in data processing, telecommunication, industrial, automatic control systems.



- Non-inductive construction.
- Self-healing property.
- High moisture resistance.
- Good solderability.

### Specification:

1. Operating Temperature:  $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$
2. Capacitance Range:  $0.01 \mu\text{F} \sim 6.8 \mu\text{F}$
3. Capacitance Tolerance:  $\pm 5\%$ (J),  $\pm 10\%$ (K),  $\pm 20\%$ (M).
4. Rated Voltage: 100VDC, 250VDC, 400VDC, 630VDC
5. Dissipation Factor: 1.0% MAX. at 1KHz,  $25^{\circ}\text{C}$
6. Insulation Resistance:  $> 30,000 \text{ M}\Omega$  ( $C \leq 0.33 \mu\text{F}$ )  
 $> 10,000 \text{ M}\Omega \cdot \mu\text{F}$  ( $C > 0.33 \mu\text{F}$ )

Unit: mm

RV	100VDC	250VDC	400VDC	630VDC
TYPE				
CAP( $\mu\text{F}$ )				
0.010				C1
0.015	C1	C1	C1	C2
0.022				
0.033	C2	C2	C2	C3
0.047				D2
0.068	C1	C1	D1	D2
0.1	C1	C1	D1	D3
0.15	C1	C3	D2	E2
0.22	C2	D1	E1	E3
0.33	C3	D2	E2	F1
0.47	D1	D3	E3	F2

0.68	D2	E2	E4	
1.0	D3	E2	F1	
1.5	E2	E4	F2	
2.2	E2	F1		
3.3	E4	F2		
4.7	F1			
6.8	F2			

Unit: mm

SIZE	W	H	T	P ± 1	dΦ
TYPE					
C1	13.0	9.0	4.0	10.0	0.6
C2	13.0	11.0	5.0	10.0	0.6
C3	13.0	12.0	6.0	10.0	0.6
D1	18.0	11.0	5.0	15.0	0.6
D2	18.0	12.0	6.0	15.0	0.8
D3	18.0	13.5	7.5	15.0	0.8
D4	18.0	14.5	8.5	15.0	0.8
E1	26.5	15.0	6.0	20.0	0.8
E2	26.5	16.5	7.0	20.0	0.8
E3	26.5	17.5	8.5	20.0	0.8
E4	26.5	19.0	10.0	20.0	0.8
F1	32.0	20.0	11.0	26.0	0.8
F2	32.0	22.0	13.0	26.0	0.8